

Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L1	4	("5276955" or "6096649" or "4518112" or "5401913").pn. and wire	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 10:00
L3	6	("5276955" or "6096649" or "4518112" or "5401913").pn. and (AU or gold)	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 10:03
L5	4	1 and gold and wire	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 10:05
L9	822	438/678.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:14
L10	756	438/685.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:14

L11	373	438/686.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:15
L12	1380	228/4.5.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:15
L13	751	228/904.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:16
L14	1656	438/687.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:16
L15	822	438/678.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:16
L16	138	438/679.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:17

L17	756	438/685.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:17
L18	373	438/686.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:17
L19	1656	438/687.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:17
L20	483	438/761.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:17
L21	396	438/762.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:18
L23	424	257/768.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:18

L24	211	257/736.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:18
L25	1423	257/751.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:18
L26	3602	257/758.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:18
L27	597	257/764.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/08 11:18
S13 0	7	S128 and metal\$5 and wire and (copper or Cu)and interconnect and ((Au-Sn) or (Au-In) or AU or Sn or In or gold or Tin or indium) and alloy	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/06 17:41

S13 1	493	metal\$5 same interconnect same wire same integrated with circuit same ((Au-Sn) or (Au-In) or AU or Sn or In or gold or Tin or indium)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/06 17:44
S13 2	32	metal\$5 with interconnect with wire with integrated with circuit with ((Au-Sn) or (Au-In) or AU or Sn or In or gold or Tin or indium)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/06 17:49
S13 3	50	low adj pressure with wire with bond\$3	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/06 17:51
S13 4	4	S133 and (Cu or copper or gold or AU or indium or Sn or tin) and interconnect	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/06 17:58
S13 8	751	228/904.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 13:20

S13 9	192	S138 and (gold or AU or Indium or In or Tin or Sn) near20 (alloy or wire)	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 13:20
S14 0	2	S139 and copper and interconnect	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 13:20
S14 2	1380	228/4.5.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 13:20
S14 3	717	S142 and (gold or AU or Indium or In or Tin or Sn) near20 (alloy or wire)	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 13:20
S14 4	3	S143 and copper near50 interconnect	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 13:26
S14 6	9	S143 and copper same interconnect	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 14:40

S14 9	245	semiconductor near50 device near50 conductive near50 layer with (gold or Au or indium or In or Sn or Tn) and copper near50 interconnect	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 14:47
S15 1	11	substrate with (copper or Cu) near50 interconnect near50 layer with (gold or Au or indium or In or Sn or Tn) and (gold or metallic) near50 wire	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 15:30
S15 2	3333	(gold or Au or Tin or Sn or indium or In) adj alloy near20 solder	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 15:37
S15 3	56	S152 and interconnect near5 (copper or Cu)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 15:35
S15 8	16	S155 and (gold or Au or Tin or Sn or indium or In) and interconnect near5 (copper or Cu)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 15:58

S16 0	2	S159 and (gold or Au or Tin or Sn or indium or In) and interconnect near5 (copper or Cu)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 16:00
S16 1	78	S159 and (gold or Au or Tin or Sn or indium or In)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 16:01
S16 4	32	(gold or Au or Tin or Sn or indium or In) same vary\$3 same alloy adj material same melt\$3 adj point	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/02/07 16:03